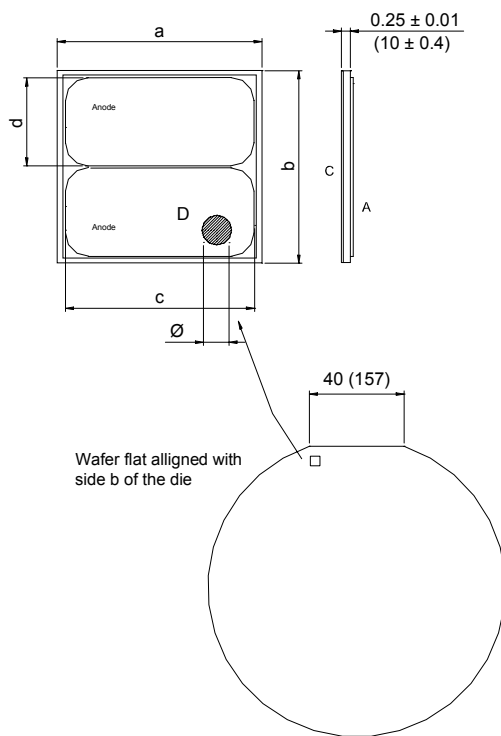


International
IOR Rectifier

SC202.....5.. Series

SCHOTTKY DIE 200 x 200 mils (Monolithic Dual)



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).

2. CONTROLLING DIMENSION: (MILS).

3. DIMENSIONS AND TOLERANCES:

$a = 5.08 \pm 0.01$

(200 $\pm$ 0, - 0.4)

$b = 5.08 \pm 0.01$

(200 $\pm$ 0, - 0.4)

$c = 4.92 \pm 0.01$

(193 $\pm$ 0, - 0.4)

$d = 2.43 \pm 0.01$

(95 $\pm$ 0, - 0.4)

$\varnothing = 1 \pm 0.15$

(40 $\pm$ 6)

4. LETTER DESIGNATION:

A = Anode (Top Metal)

C = Cathode (Back Metal)

D = Reject Ink Dot (only on non-conforming dies)

5. SAWING:

Recommended Blade

SEMITEC S1025 QS00 Blade

Sawing Street

0.05 ± 0.005

(2 $\pm$ 0, - 0.2)

NOT TO SCALE

SC202.....5. Series

Preliminary Data Sheet I0508J rev. B 05/01

International
IR Rectifier

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Max. I _R @ 25°C (mA)	(*) Max. V _F @ I _F (V)
SC202 S 020A5	150	20	8	0.42 V @ 40A per die, T _J = 25°C
SC202 S 030A5	150	30	2	0.46V @ 30A per die, T _J = 25°C
SC202 S 045A5	150	45	2	0.51 V @ 20A per die, T _J = 25°C
SC202 S 060A5	150	60	2	0.54V @ 15A per die, T _J = 25°C
SC202 H 100A5	150	100	0.55	0.69 V @ 10A per die, T _J = 25°C

(*) For reference only, V_F do not include voltage drop across wire bonding resistance

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC202..... A 5..	Bondable	–	Al/Si 30 kÅ	–	Ti 1 kÅ	Ni 4 kÅ	Ag 6 kÅ

Visual Inspection : see IR internal Spec. # 6373-2064

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

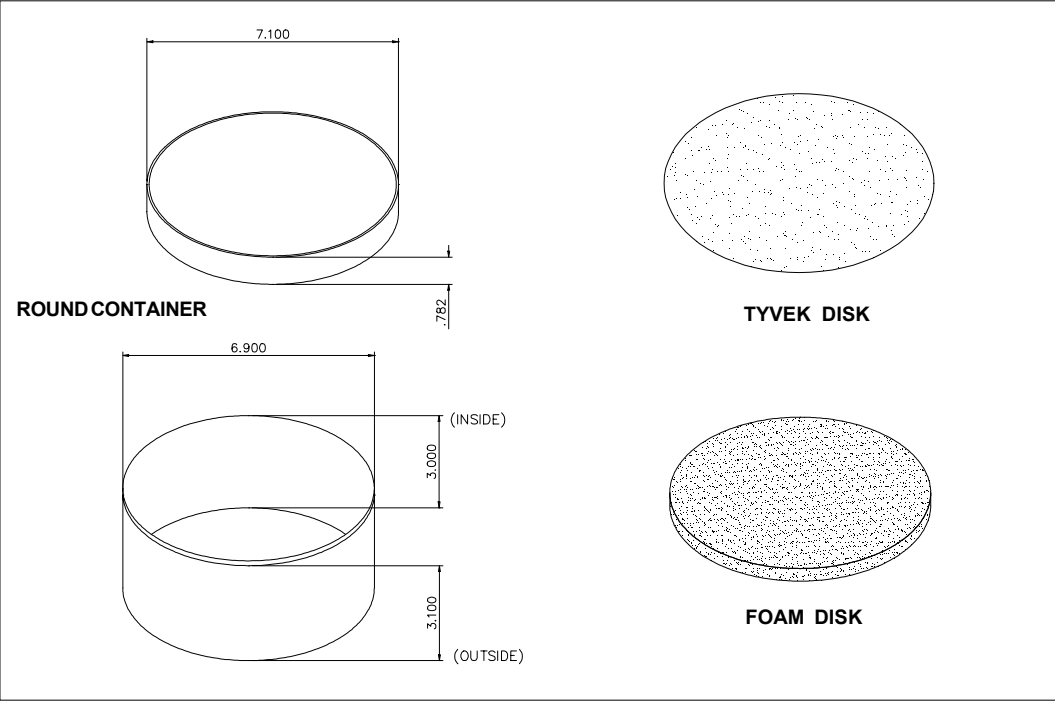
Device #	Description	Minimum Order Quantity Wafer in Sale Package
SC202..... 5B .	Inked Probed Unsawn Wafer (Wafer in Box)	48

Ordering Information Table

Device Code						
SC202S060A5B						
1234567						
1	- Schottky Die					
2	- Chip Dimension in Mils: 200 x 200 Dual Monolithic					
3	- Process (see Electrical Characteristics Table)					
4	- Voltage code: Code = V_{RRM}					
5	- Chip surface metallization (Al)					
6	- Wafer Diameter in inches					
7	- Packaging: B = inked probed unsawn wafers (in box)					

H = 830 Process
R = OR'ing Process
S = Standard Process

Wafer in Box



WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245 U.S.A. Tel: (310) 322 3331. Fax: (310) 322 3332.
EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, U.K. Tel: ++ 44 1883 732020. Fax: ++ 44 1883 733408.
IR CANADA: 15 Lincoln Court, Brampton, Markham, Ontario L6T3Z2. Tel: (905) 453 2200. Fax: (905) 475 8801.
IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg. Tel: ++ 49 6172 96590. Fax: ++ 49 6172 965933.
IR ITALY: Via Liguria 49, 10071 Borgaro, Torino. Tel: ++ 39 11 4510111. Fax: ++ 39 11 4510220.
IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo, Japan 171. Tel: 81 3 3983 0086.
IR SOUTHEAST ASIA: 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994. Tel: ++ 65 838 4630.
IR TAIWAN: 16 Fl. Suite D.207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan. Tel: 886 2 2377 9936.

<http://www.irf.com>

Fax-On-Demand: +44 1883 733420

Data and specifications subject to change without notice.